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	L#	Hits	EAST Search Text	DBs	Time Stamp	Туре
1	L1	7	(("5745594") or ("5962862") or ("5987172") or ("5943441")).PN.	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 17:52	IS&R
2	L2	11106 5	(camera OR image OR video OR picture OR photo OR photograph) WITH (merg\$3 OR combin\$3 OR join\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
3	L3	3382	wafer WITH fragment\$6	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
4	L4	19	L2 AND L3	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
5	L5	9	("4713551" "4786816" "5466945" "5471541" "5644140" "5796486" "5798532" "5852300" "6324298").PN.		2004/03/11 17:59	BRS
6	L6	3	5644140.URPN.	USPAT	2004/03/11 18:03	BRS
7	L7	219	log WITH (cyclical OR recycl\$3 OR recirculat\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:55	BRS
8	L8	16	L7 SAME (trigger\$3 OR signal\$4 OR stop\$4 OR activat\$3 OR prompt\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:25	BRS
9	L9	6	L7 SAME (camera OR image OR video OR picture OR photo OR photograph)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:26	BRS

	L#	Hits	Search Text	DBs	Time Stamp	Туре
10	L1 0	22	L7 SAME (monitor\$3 OR check\$3 OR inspect\$3 OR examin\$3 OR observ\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:25	BRS
11	L1 1	12605 0	(log OR history OR buffer) SAME (monitor\$3 OR check\$3 OR inspect\$3 OR examin\$3 OR observ\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:27	BRS
12	L1 2	39067	L11 SAME (trigger\$3 OR signal\$4 OR stop\$4 OR activat\$3 OR prompt\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
13	L1 3	6434	L12 SAME (camera OR image OR video OR picture OR photo OR photograph)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:27	BRS
14	L1 4	56523	(log OR history OR buffer) WITH (monitor\$3 OR check\$3 OR inspect\$3 OR examin\$3 OR observ\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:27	BRS
15	L1 5	16038	L14 SAME (trigger\$3 OR signal\$4 OR stop\$4 OR activat\$3 OR prompt\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:27	BRS
16	L1 6	9104	L14 WITH (trigger\$3 OR signal\$4 OR stop\$4 OR activat\$3 OR prompt\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:50	BRS

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	L#	Hits	Search Text	DBs	Time Stamp	Туре
17	L1 7	1644	L16 SAME (camera OR image OR video OR picture OR photo OR photograph)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
18	L1 8	1333	L16 WITH (camera OR image OR video OR picture OR photo OR photograph)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
19	L1 9	491	L18 AND (semiconductor OR integrated ADJ circuit OR IC OR wafer OR chip)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
20	L2 0	40	L18 SAME (semiconductor OR integrated ADJ circuit OR IC OR wafer OR chip)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:29	BRS
21	L2 1	2452	buffer WITH (cyclical OR recycl\$3 OR recirculat\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:49	BRS
22	L2 2	324	L21 WITH (trigger\$3 OR signal\$4 OR stop\$4 OR activat\$3 OR prompt\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:50	BRS
23	L2 3	22	L22 WITH (camera OR image OR video OR picture OR photo OR photograph)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:53	BRS

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	L#	Hits	Search Text	DBs	Time Stamp	Туре
24	L2 4	2116	security SAME (photo OR picture OR camera) SAME (history OR stor\$3 OR archiv\$3 OR buffer\$4 OR log\$4)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:55	BRS
25	L2 5	5002	security SAME (photo OR picture OR camera OR image) SAME (history OR stor\$3 OR archiv\$3 OR buffer\$4 OR log\$4)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:54	BRS
26	L2 6	1533	security WITH (photo OR picture OR camera OR image) WITH (history OR stor\$3 OR archiv\$3 OR buffer\$4 OR log\$4)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:13	BRS
27	L2 7	5	L26 WITH (cyclical OR recycl\$3 OR recirculat\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:13	BRS
28	L2 8	5	L26 SAME (cyclical OR recycl\$3 OR recirculat\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 18:57	BRS
29	L2 9	52	L26 SAME (temporar\$3 OR permanent\$2)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:03	BRS
30	L3 0	50	event WITH log\$4 WITH (cyclical OR recirculat\$3 OR recycl\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:04	BRS

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	L#	Hits	Search Text	DBs	Time Stamp	Тур
31	L3 1	16287	monitor\$3 WITH (photo OR picture OR camera OR image) WITH (history OR stor\$3 OR archiv\$3 OR buffer\$4 OR log\$4)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
32	L3 2	600	L31 WITH (temporar\$3 OR permanent\$2 OR cyclical\$2 OR recycl\$3 OR recirculat\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
33	L3 3	3	L31 WITH (temporar\$3 OR permanent\$2) WITH (cyclical\$2 OR recycl\$3 OR recirculat\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:18	BRS
34	L3 4	4	3804978.URPN.	USPAT	2004/03/11 19:16	BRS
35	L3 5	2	3900706.URPN.	USPAT	2004/03/11 19:16	BRS
36	L3 6	3	RE31239.URPN.	USPAT	2004/03/11 19:17	BRS
37	L3 7	9	L31 SAME (temporar\$3 OR permanent\$2) SAME (cyclical\$2 OR recycl\$3 OR recirculat\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM TDB	2004/03/11 19:26	BRS
38	L3 8	15	("4555561" "4752897" "5070468" "5192999" "5208745" "5210526" "5258837" "5260878" "5270811" "5278643" "5284164" "5353238" "5412400" "5416725"	USPAT	2004/03/11 19:19	BRS
39	L3 9	83973	von buhr.xa,xp.	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:26	BRS
40	L4 0	337	von ADJ buhr.xa,xp.	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:27	BRS

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	L#	Hits	Search Text	DBs	Time Stamp	Туре
41	L4 1	84	L40 AND buffer	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:28	BRS
42	L4 2	2	L41 AND recirculat\$3	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
43	L4 3	47	napiorkowski.xa,xp.	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
44	L4 4	21	L43 AND buffer	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:28	BRS
45	L4 5	1	L44 AND recirculat\$3	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
46	L4 6	232	(L40 OR L43) AND log\$4	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:31	BRS
47	L4 7	4	(L40 OR L43) AND recirculat\$3	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:29	BRS

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	L#	Hits	Search Text	DBs	Time Stamp	Туре
48	L4 8	191	L46 AND (trigger\$3 OR signal\$4 OR stop\$4 OR activat\$3 OR prompt\$3)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:31	BRS
49	L4 9	0	L48 AND eent	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
50	L5 0	100	L48 AND event	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11	BRS
51	L5 1	49	(L40 OR L43) AND log\$4 SAME event	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:37	BRS
52	L5 2	57	L50 NOT L51	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:41	BRS
53	L5 3	125	L46 NOT (L42 OR L45 OR L47 OR L50 OR L51)	USPAT; US-PGPU B; EPO; JPO; DERWEN T; IBM_TDB	2004/03/11 19:43	BRS
54	L5 4	24	("4878167" "5155678" "5191651" "5280611" "5339427" "5345590" "5394554" "5410695" "5463736" "5471631" "5485608" "5493668" "5530850" "5537574" "5537588" "5551003" "5737600" "5832515" "5920875" "5956735" "5999935" "6076095" "6092084" "6125393").PN.		2004/03/11 19:47	BRS

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	1	Document ID	Sourc e	Issue Date	Title	Current OR	Inventor	2	3	4	5
1	Ø	US 200302021 78 A1	US-PG PUB	20031030	Semiconductor wafer inspection apparatus	356/237. 2	Tsuji, Haruyuki et al.				Ø
2	Ø	US 200100437 35 A1	US-PG PUB	20011122	DETECTION OF WAFER FRAGMENTS IN A WAFER PROCESSING	382/149	SMARGIASSI, EUGENE et al.				
3	Ø	US 6535628 B2	USPA T		Detection of wafer fragments in a wafer processing apparatus	382/149	Smargiassi, Eugene et al.				
4		CN 1405853 A	DERW ENT	20030326	Method for tracing wafer boundary		XU, Q	Ø			Ø
5	Ø	WO 200022655 A	DERW ENT	20030507	Wafer fragments analyzing system for semiconductor production, has image acquisition device to acquire image of wafer edge portion where illumination source generates back-illuminating radiation for wafer		AHMAD, W R et al.				
6	Ø	US 6064429 A	USPA T	20000516	Foreign object video detection and alert system	348/128	Belk, John Huntley et al.				
7		US 5909276 A	USPA T	19990601	Optical inspection module and method for detecting particles and defects on substrates in integrated process tools	356/237. 2	Kinney, Patrick D. et al.	Ø			
8		US 5659630 A	USPA T	19970819	Advanced manufacturing inspection system	382/149	Forslund, Donald Charles	Ø			
9		US 5592295 A		19970107	Apparatus and method for semiconductor wafer edge inspection	356/426	Stanton, Leslie G. et al.				
10		US 4812664 A		19890314	Apparatus for scanning a flat surface to detect defects	18	G.				
11		US 4659220 A	USPA T	19870421	Optical inspection system for semiconductor wafers	356/237. 5	Bronte, Joseph J. et al.	Ø			
12		US 4352016 A	USPA T	19820 928	Method and apparatus for determining the quality of a semiconductor surface	250/358. 1	Duffy, Michael T. et al.	Ø			
13		US 4652757 A	USPA T	1987 0324	Method and apparatus for optically determining defects in a semiconductor material	250/360. 1	Carver, Gary E.	Ø			
14	Ø	US 6452150 B1	USPA T	2002 0917	Cassette measuring system	250/208. 1	Mori, Kunihiko et al.				
15		US 6324298 B1	USPA T	20011 127	Automated wafer defect inspection system and a process of performing such inspection	382/149	O'Dell, Jeffrey et al.	Ø			
16		US 5644140 A	USPA T	1997 0701	Apparatus for checking semiconductor wafers with complementary light sources and two cameras		Biedermann, Ernst et al.	⊠			
17			DERW ENT	20020607	Object utilization log management method in operating system, involves storing monitoring data that recycles utilization log of object in memory			⊠			⊠

	1	Document ID	Sourc e	Issue Date	Title	Current OR	Inventor	2	3	4	5
18		US 6404498 B1	USPA T	20020611	Manufacturing method of semiconductor substrate and method and apparatus for inspecting defects of patterns on an object to be	356/394	Maeda, Shunji et al.	×			
19		US 6265736 B1	USPA T	20 010724	lmage pick-up apparatus	257/232	Dillen, Bartholomeus G. M. H. et al.	×			
20		US 6263099 B1	USPA T	20010717	Manufacturing method of semiconductor substrate and method and apparatus for inspecting defects of patterns of an object to be	382/149	Maeda, Shunji et al.	Ø			
21		US 5774222 A	USPA T	19980 630	Manufacturing method of semiconductor substrative and method and apparatus for inspecting defects of patterns on an object to be inspected	356/394	Maeda, Shunji et al.	⊠			
22		US 5412705 A	USPA T	19950 502	X-ray examination apparatus with an imaging arrangement having a plurality of image sensors		Snoeren, Rudolph M. et al.	Ø			
23		US 5771374 A	USPA T	1998062 3	Event driven programmer logic controller processor arrangement with buffered inputs and method of operation of the same	713/502	Burshtein, Anat et al.	×			
24	Ø	US 5625572 A	USPA T	19970 429	Multimedia proc ess monitor and control syste m	702/183	Yonekura, Toshiaki et al.				

	1 [1]	Document ID	Sourc 8	Issue Date	Title	Current OR	Inventor	2 [1]	3	4	5
1	Ø	US 4638289 A	USPA T	19870120	Accident data recorder	246/45	Zottnik, Edmund	Ø			
2	Ø	US 6163338 A	USPA T	20001219	Apparatus and method for recapture of realtime events	348/148	Johnson, Dan et al.	Ø			